

THE CHINESE UNIVERSITY OF HONG KONG
Office of Admissions and Financial Aid (OAFA)

HSBC Scholarships and Innovation and Technology Scholarship

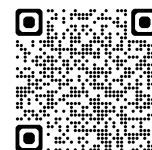
With the generous donations from HSBC, a number of awards under **HSBC Greater Bay Area (Hong Kong) Scholarship**, **HSBC Hong Kong Scholarship**, **HSBC Overseas Scholarship** as well as **Innovation and Technology Scholarship** have been offered to **LOCAL** (Hong Kong permanent residents) **full-time undergraduate students** over the past years.

Briefing Session

If you are interested in these scholarships, do not miss the upcoming briefing session. Details of the briefing session are as follows:

Date : 15 November 2024 (Friday)
Time : 4:30 pm – 5:30 pm
Venue : LT4, Yasumoto International Academic Park, CUHK

To **register** for the briefing session, please complete and submit **by 11 November 2024** an online registration form which is obtainable from OAFA website at <http://admission.cuhk.edu.hk/> (Fees and Financing Your Studies → News and Events). Confirmation will be sent to successful registrants by email on or before 12 November 2024.



For enquiries **about the briefing session**, please contact the Scholarships and Financial Aid Section, OAFA at sfas@cuhk.edu.hk or 3943 7204.

News and Events
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Below is the general information, based the previous exercise, on the scholarships which will invite for application soon. Details are subject to change.

HSBC Greater Bay Area (Hong Kong) Scholarship

Awardees of this Scholarship will receive an award of HK\$80,000, and will also be offered learning opportunities (e.g. mentorship and internship). To be eligible for this Scholarship, applicants must have a **minimum cumulative GPA score of 3.0 or top 15% of class**.

HSBC Hong Kong Scholarship

Awardees of this Scholarship will receive an award of HK\$50,000, and will also be offered learning opportunities (e.g. mentorship and internship). To be eligible for this Scholarship, applicants must have a **minimum cumulative GPA score of 3.7 or top 3% of class**.

HSBC Overseas Scholarship

This Scholarship, with maximum award of HK\$300,000 each, supports the selected candidates to spend **a semester or an academic year** of their studies **as visiting students or exchange students at an overseas university** in the next academic year. To be eligible for this Scholarship, applicants must be **non-final-year undergraduates** who have a **minimum cumulative GPA score of 3.7 or top 3% of class**.

Innovation and Technology Scholarship

This Scholarship, with maximum award of HK\$150,000 each, will financially support **non-final-year undergraduates with InnoTech passion**, who are **undertaking ANY degree** and preferably have a **cumulative GPA of at least 3.0**, to participate in **attachment programme(s) overseas and in Mainland China** in the next academic year. In addition, the scholarship recipients will be offered an opportunity to join the mentorship programme, service project programme, local internship programme and Ideations and Achievements Showcase.

25 October 2024